

Electronic Acknowledgement Receipt

EFS ID:	6906586
Application Number:	10549356
International Application Number:	
Confirmation Number:	1717
Title of Invention:	Organosilicate resin formulation for use in microelectronic devices
First Named Inventor/Applicant Name:	Kiran K. Baikerikar
Customer Number:	00109
Filer:	Susan M. Zerull
Filer Authorized By:	
Attorney Docket Number:	62657A
Receipt Date:	29-JAN-2010
Filing Date:	15-FEB-2007
Time Stamp:	10:25:16
Application Type:	U.S. National Stage under 35 USC 371

Payment information:

Submitted with Payment	no
------------------------	----

File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1	Response to Election / Restriction Filed	62657A_US_20100129_SMZ_R estricition_Response.pdf	28090 cefe7c7b38a78218d8d2006d7ff99323b4c8 7e3c	no	7

Warnings:

Information:

2	Information Disclosure Statement (IDS) Filed (SB/08)	62657A_US_20100128_SMZ_S upplemental_IDS_SB_08.pdf	40633	no	6
			80cdc649dd7149b169e45e09e084903214 b11102		
Warnings:					
Information:					
This is not an USPTO supplied IDS fillable form					
3	Transmittal Letter	62657A_US_20100129_SMZ_S upplemental_Information_Disc losure_Statement.pdf	5616	no	2
			59ad7e18869e9f77e30c7ab100a76206900 9555a		
Warnings:					
Information:					
4	NPL Documents	Dammel_R_R_Antireflective_C oatings_SPIE_2004.pdf	62483	no	1
			d1d9f29c7819f8e003868bb8c51a8eda2f64 e12c		
Warnings:					
Information:					
5	NPL Documents	Drage_et_al.pdf	461360	no	8
			61c8e67b747ba36e5f125778f10069160b3 7252c		
Warnings:					
Information:					
6	NPL Documents	Hendricks_1996_Polymer_Prep rints.pdf	2361783	no	2
			9f1b3d4bc61d3e5aba2ba1234815577e386 fae47		
Warnings:					
Information:					
7	NPL Documents	Kunz_Proceedings_of_SPIE.pdf	2265985	no	14
			f9976d713dfed98b75e793ed75762d843f3 6cfe7		
Warnings:					
Information:					
8	NPL Documents	Lin_et_al_Dual_Layer_Inorgani c_SiON_Bottom_ARC.pdf	3263015	no	12
			17a60f3c4b6ddf18f6115aedf8eebfc377c92 c4c		
Warnings:					
Information:					
9	NPL Documents	Onishi_Journal_Photopolymer _Science.pdf	161134	no	4
			9c214b3cca84aac559201a651df4b74ccc9a 4402		
Warnings:					
Information:					
10	NPL Documents	Singer_1999_Semiconductor_I nternational.pdf	5169425	no	6
			aa97a1a6082a2c5e7eedf77fb788ef3097cd 6137		

Warnings:	
Information:	
Total Files Size (in bytes):	13819524
<p>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</p> <p><u>New Applications Under 35 U.S.C. 111</u> If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p><u>National Stage of an International Application under 35 U.S.C. 371</u> If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p> <p><u>New International Application Filed with the USPTO as a Receiving Office</u> If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.</p>	